

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kanguo Cheng</td> <td>06/27/2012</td> </tr> <tr> <td>Bruce B. Doris</td> <td>06/28/2012</td> </tr> <tr> <td>Balasubramanian S. Haran</td> <td>06/27/2012</td> </tr> <tr> <td>Shom Ponoth</td> <td>06/27/2012</td> </tr> <tr> <td>Theodorus E Standaert</td> <td>06/28/2012</td> </tr> <tr> <td>Tenko Yamashita</td> <td>06/28/2012</td> </tr> </tbody> </table>		Name	Execution Date	Kanguo Cheng	06/27/2012	Bruce B. Doris	06/28/2012	Balasubramanian S. Haran	06/27/2012	Shom Ponoth	06/27/2012	Theodorus E Standaert	06/28/2012	Tenko Yamashita	06/28/2012
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Shom Ponoth	06/27/2012														
Theodorus E Standaert	06/28/2012														
Tenko Yamashita	06/28/2012														
RECEIVING PARTY DATA															
Name:	International Business Machines Corporation														
Street Address:	New Orchard Road														
City:	Armonk														
State/Country:	NEW YORK														
Postal Code:	10504														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13537141</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13537141										
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Application Number:	13537141														
CORRESPONDENCE DATA															
Fax Number:	(845)892-6363														
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ATTORNEY DOCKET NUMBER:	FIS920120079US1														

CH \$40.00 13537141

NAME OF SUBMITTER:

Joseph Petrokaitis

Total Attachments: 6

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IBM DOCKET NUMBER: FIS920120079US1

ASSIGNMENT

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

Title of the Invention: UNDERCUT INSULATING REGIONS FOR SILICON-ON-INSULATOR
DEVICE

and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having:

Serial Number: _____ (insert series code and serial number here if/when available)

Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned Inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;


Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Each undersigned Inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned Inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent application Serial Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

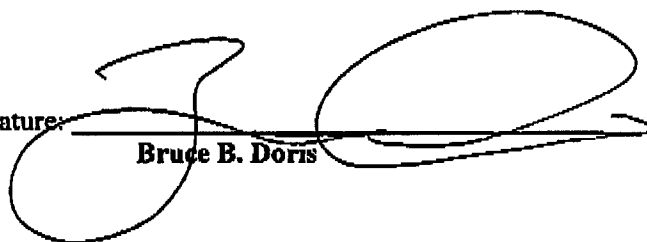
[Inventor Signature Page(s) Follows]

IBM DOCKET NUMBER: FIS920120079US1

1 Executed by Inventor 1

Signature:  Date: 6/27/2012
Kangguo Cheng

1 Executed by Inventor 2

Signature:  Date: 6/28/12
Bruce B. Doris

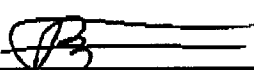
1 Executed by Inventor 3

Signature:  Date: 6/27/12
Balasubramanian S. Haran

1 Executed by Inventor 4

Signature: _____ Date: _____
Shom Ponoth

1 Executed by Inventor 5

Signature:  Date: 6/28/2012
Theodorus E. Standaert

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1 Executed by Inventor 6

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Tenko Yamashita

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